IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Joseph Kuczynksi et al : Date: March 18, 2004

Group Art Unit: Unassigned : IBM Corporation

Examiner: Unassigned : Intellectual Property Law

Serial No.: Unassigned : Dept. 917, Bldg. 006-1

Filed: Herewith : 3605 Highway 52 North

Title: LAND GRID ARRAY (LGA) : Rochester, Minnesota 559501

INTERPOSER WITH ADHESIVE-RETAINED CONTACTS AND METHOD OF MANUFACTURE

INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §1.97

Commissioner for Patents PO Box 1450 Alexandria, VA 22313-1450

Sir:

Applicants request that the information listed on the attached Form PTO/SB/08A be considered by the Office during the pendency of the above entitled application, pursuant to 37 C.F.R. §1.97. In accordance with 37 C.F.R. §1.97(h), the filing of this Information Disclosure Statement shall not constitute an admission that any information cited therein is, or is considered to be, material to patentability as defined in 37 C.F.R. §1.56(b). In the interest of full and complete disclosure to the Office, some or all of the art cited herein may not be considered by Applicant(s) or the Undersigned to be material under the new standard of materiality defined in 37 C.F.R. §1.56(b), enacted March 16, 1992, but may be material under the old standard of materiality defined in 37 C.F.R. §1.56(a), last amended on November 28, 1988, or may merely be technical background which may be of interest to the Examiner. In accordance with 37 C.F.R. §1.97(g), the filing of this Information Disclosure Statement shall not be construed to mean that a search has been made.

This Information Disclosure Statement is being filed under 37 C.F.R. §1.97(b)(1) within three months of the filing date of the present application. Accordingly no filing fee is required.

Date: March 18, 2004

IBM Corporation Intellectual Property Law, Dept. 917 3605 Highway 52 North Rochester, MN 55901

(507) 253-2555 voice (507) 253-2382 fax Respectfully submitted

By Leslie J. Payne, Aytorney

Registration No. 26,378

Application Number.: Unassigned PTO/SB/08A Filing Date: Herewith Kuczynski et al INFORMATION DISCLOSURE First Named Inventor: Unassigned STATEMENT BY APPLICANT Art Unit: **Unassigned Examiner Name:** ROC920040017US1 Sheet 1 of 2 Attorney Docket Number.:

U.S. PATENT DOCUMENTS

Examiner Initials*	Cite No.1	Document Number Number - Kind Code ² (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns or Lines Where Relevant Passages or Figs. Appear
	AA	US - 6264476B1	07/24/2001	Che-yu Li et al	
	AB	US - 6528984B2	03/04/2003	Brian Samuel Beaman et al	
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FOREIGN PATENT DOCUMENTS

		Foreign Patent Document		Name of Patentee or	Pages, Columns or Lines Where	
Examiner Initials	Cite No. ¹	Country ³ - Number ⁴ - Kind Code ⁵ Code (if known)	Publication Date MM-DD- YYYY	Applicant of Cited Document	Relevant Passages or Figs. Appear	T ⁶
	AC	JP -11 - 31541 - A	02/02/1999	Kawabe		X
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Examiner Signature	Date Considered	T
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance <u>and</u> not considered. Include copy of this form with next communication to applicant.

Applicant's unique citation designation number (optional). ² See Kind Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3).

⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. ⁶ Applicant is to place a check mark here if English language translation is attached.

PTO/SB/08A Application Number.: Unassigned
Filing Date: Herewith
INFORMATION DISCLOSURE First Named Inventor: Kuczynski et al
STATEMENT BY APPLICANT Art Unit: Unassigned
Examiner Name: Unassigned

Sheet _2_ of _2_ Attorney Docket Number.: ROC920040017US1

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS

		Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate),	
Examiner	Cite	title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s),	
Initials No.1		volume-issue number(s), publisher, city and or country where published.	
	AD	IBM Technical Disclosure Bulletin, Vol. 33, No. 5, October 1990, "Compressible-	T ²
		Contact Interconnection Scheme" by K. J. Puttlitz and H. Wenskus, pp. 394-395	<u> </u>
	AE	US Patent Application Publication 2001/0001748A1, May 24, 2001, "Conduction	
		Assist Member and Manufacturing Method of the Same" by Toshimasa Ochiai	
	AF	US Patent Application Publication 2001/0020546A1, September 13, 2001, "Electrical	
		Contact Structures Formed by Configuring a Flexible Wire to Have a Springable Shape	
		And Overcoating the Wire With at Least One Layer of a Resilient Conductive	
		Material, Methods of Mounting the Contact Structures to Electronic Components, and	
		Applications for Employing the Contact Structures" by Benjamin N. Eldridge et al	
	AG	US Patent Application Publication 2001/0024892A1, September 27, 2001, "Contact	
		Sheet" by Toshimasa Ochiai	
	AH	US Patent Application Publication 2003/0146510A1, August 7, 2003, "Elastomer	
		Interposer for Grid Array Packages and Method of Manufacturing the Same" by	
		Ray Chien	
	AI	US Patent Application Publication 2003/0003784A1, January 2, 2003, "Interposer	
	 	Assembly" by Douglas A. Neidich	

Examiner Signature	 Date Considered	

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Applicant's unique citation designation number (optional).

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